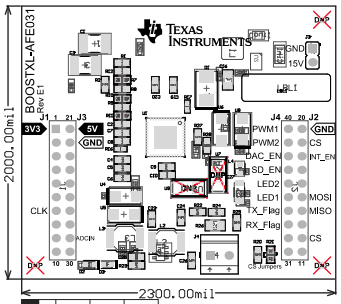
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	8.00mil	4.2	
5	POWER	Copper	1.40mil		
6	Dielectric 2	FR-4	40.00mil	4.2	
7	GND	Copper	1.40mil		
8	Dielectric 3	FR-4	8.00mil	4.2	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION	
MIN. TRACK WIDTH:	8 MIL
MIN. CLEARANCE:	0.2 mm
MIN. VIA PAD SIZE:	24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL	
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED):	+/- 3 MIL
MATERIAL:	[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS:	[X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE:	[X] ANSI IPC-6012 TYPE 3 CLASS 2 / [ ] OTHER +/-
BOW & TWIST:	[X] ANSI IPC-6012 TYPE 3 CLASS 2 / [ ] OTHER +/-
DRILLING:	
REFERENCE:	[X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS:	[X] 20-30 um [ ] OTHER
BOARD FINISH:	
SILKSCREEN:	[X] TOP [X] BOTTOM
SILKSCREEN COLOR:	[X] WHITE [ ] OTHER
SOLDER RESIST COLOR:	[ ] GREEN [X] OTHER RED
	[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH:	[X] IMMERSION GOLD (ENIG) [ ] ENEPIG
	[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL:	[ ] CUT AND TRIM PER M1 BOARD OUTLINE
	[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION:	MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
	[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
	[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS. PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER	
ADDITIONAL REQUIREMENTS:	
MICROSECTION:	[ ] YES
BARE BOARD ELEC. TEST:	[ ] NONE [X] REQUIRED [ ] PER ORDER

ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
ZZ2 ■ This Assembly Note will show in the PcbDoc and associated outputs
ZZ3 ■ This Assembly Note will show in the PcbDoc and associated outputs
ZZ4 ■ This Assembly Note will show in the PcbDoc and associated outputs



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED
ASSEMBLY VARIANT: PWM_Mode

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PROJECT TITLE:	BOOSTXL-PARTNUM
DESIGNED FOR:	Public Release
FILE NAME:	AFE031-BOOSTXL_PCB.PcbDoc
ENGINEER:	Enter name of project
LAYOUT BY:	Who did the Layout?
SCALE:	0.71
ALTIUM DESIGNER VERSION:	17.1.9.592

Q21

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	8.00mil	4.2	
5	POWER	Copper	1.40mil		
6	Dielectric 2	FR-4	40.00mil	4.2	
7	GND	Copper	1.40mil		
8	Dielectric 3	FR-4	8.00mil	4.2	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION	
MIN. TRACK WIDTH:	8 MIL
MIN. CLEARANCE:	0.2 mm
MIN. VIA PAD SIZE:	24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL	
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED):	+/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [ ] GREEN [X] OTHER RED
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

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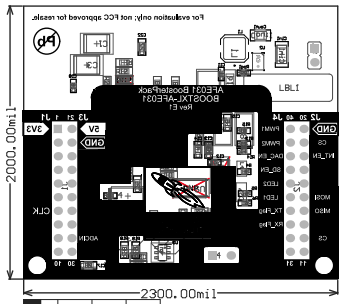

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED
ASSEMBLY VARIANT: PWM_Mode

TEXAS INSTRUMENTS

PROJECT TITLE: BOOSTXL-PARTNUM
DESIGNED FOR: Public Release
FILE NAME: AFE031-BOOSTXL_PCB.PcbDoc

ENGINEER: Enter name of project	LAYOUT BY: Who did the Layout?
SCALE: 0.71	ALTIUM DESIGNER VERSION: 17.1.9.592

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
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10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION	
MIN. TRACK WIDTH:	8 MIL
MIN. CLEARANCE:	0.2 mm
MIN. VIA PAD SIZE:	24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [ ] GREEN [X] OTHER RED
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

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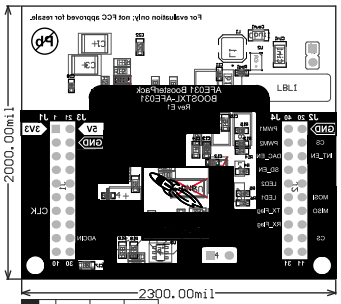

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED
ASSEMBLY VARIANT: PWM_Mode

TEXAS INSTRUMENTS

PROJECT TITLE: BOOSTXL-PARTNUM
DESIGNED FOR: Public Release
FILE NAME: AFE031-BOOSTXL_PCB.PcbDoc

ENGINEER: Enter name of project
LAYOUT BY: Who did the Layout?
SCALE: 0.71
ALTIUM DESIGNER VERSION: 17.1.9.592

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
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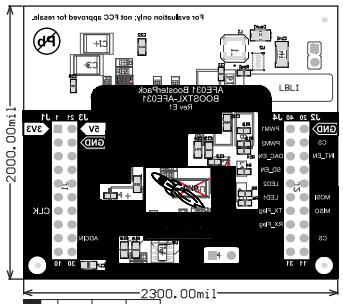

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED
ASSEMBLY VARIANT: PWM_Mode

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [ ] GREEN [X] OTHER RED
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
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ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
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[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

TEXAS INSTRUMENTS

PROJECT TITLE: BOOSTXL-PARTNUM
DESIGNED FOR: Public Release
FILE NAME: AFE031-BOOSTXL_PCB.PcbDoc

ENGINEER: Enter name of project	LAYOUT BY: Who did the Layout?
SCALE: 0.71	ALTIUM DESIGNER VERSION: 17.1.9.592

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